

AMENDMENTS TO THE SPECIFICATION

Please amend the paragraph at page 1, beginning at line 6 as follows:

This application contains subject matter similar to subject matter disclosed in co-pending U.S. patent application Serial No. 09/946,939, filed on September 06, 2001 (~~Attorney Docket No. 50103-381~~).

Please amend the paragraph at page 5, beginning at line 15 as follows:

An approach for minimizing deleterious effects on imprint quality, etc., arising from mismatch of the thermal expansion/contraction properties of the stamper/imprinter and substrate/workpiece is disclosed in commonly assigned, co-pending U.S. application Serial No. 09/946,939 (~~Attorney Docket No. 50103-381~~), which approach involves utilizing stamper/imprinters and substrate/workpieces having equal, or at least substantially similar, coefficients of thermal expansion/contraction. However, this approach has a drawback in that it is generally limited to use of identical materials for the stamper/imprinter and substrate/workpiece, effectively precluding use of significantly different materials therefor, e.g., a metal stamper/imprinter and a glass substrate/workpiece. Another drawback associated with thermal lithographic imprinting is the very long heating and cooling times required for performing the pattern embossing process, which disadvantageously results in correspondingly long cycles times (on the order of several minutes) and significantly increased cost when forming part of a high product throughput manufacturing process, e.g., manufacture of substrates for hard disk magnetic recording media.